

PRELIMINARY

TPCA8011-H

High Speed and High Efficiency DC-DC Converters
 Notebook PC Applications
 Portable Equipment Applications

- Small footprint due to small and thin package
- High speed switching
- Small gate charge: $Q_{sw} = 11 \text{ nC (typ.)}$
- Low drain-source ON resistance: $R_{DS(ON)} = 3.1 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = \text{TBD S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A (max) (}V_{DS} = 30 \text{ V)}$
- Enhancement mode: $V_{th} = 1.1 \text{ to } 2.3 \text{ V (}V_{DS} = 10 \text{ V, } I_D = 1 \text{ mA)}$

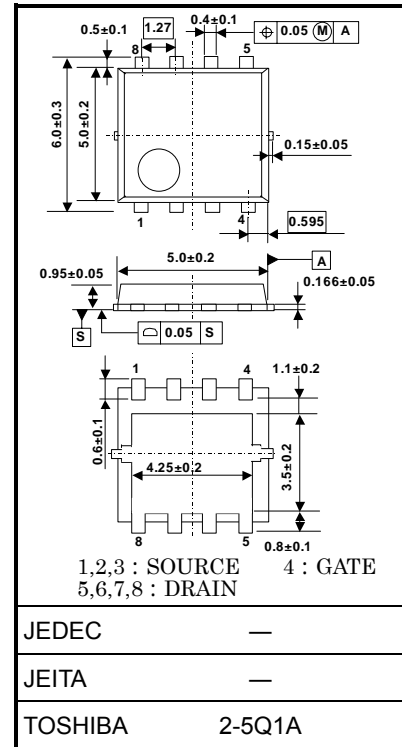
Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	20	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	20	V
Gate-source voltage		V_{GSS}	± 12	V
Drain current	DC (Note 1)	I_D	40	A
	Pulsed (Note 1)	I_{DP}	120	
Drain power dissipation ($T_c=25^\circ\text{C}$)		P_D	45	W
Drain power dissipation ($t = 10 \text{ s}$) (Note 2a)		P_D	2.8	W
Drain power dissipation ($t = 10 \text{ s}$) (Note 2b)		P_D	1.6	W
Single pulse avalanche energy (Note 3)		E_{AS}	208	mJ
Avalanche current		I_{AR}	40	A
Repetitive avalanche energy ($T_c=25^\circ\text{C}$) (Note 4)		E_{AR}	TBD	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55 to 150	$^\circ\text{C}$

Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

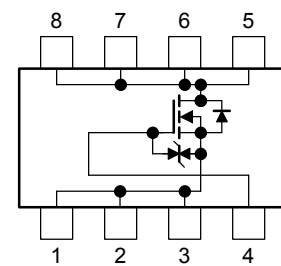
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.080 g (typ.)

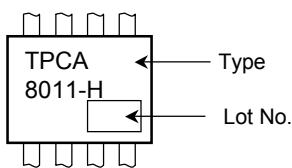
Circuit Configuration



Thermal Characteristics

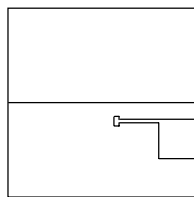
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case ($T_c=25$)	$R_{th(ch-c)}$	2.78	$^{\circ}C/W$
Thermal resistance, channel to ambient ($t = 10$ s) (Note 2a)	$R_{th(ch-a)}$	44.6	$^{\circ}C/W$
Thermal resistance, channel to ambient ($t = 10$ s) (Note 2b)	$R_{th(ch-a)}$	78.1	$^{\circ}C/W$

Marking (Note 5)

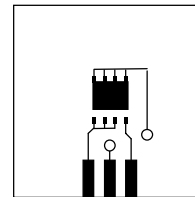


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



(a)

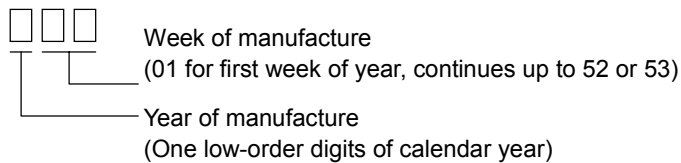


(b)

Note 3: $V_{DD} = 24$ V, $T_{ch} = 25^{\circ}C$ (initial), $L = 0.1$ mH, $R_G = 25 \Omega$, $I_{AR} = 35$ A

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: * Weekly code: (Three digits)



Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$	—	—	± 10	μA
Drain cut-OFF current		I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	—	—	10	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10mA, V_{GS} = 0V$	20	—	—	V
		$V_{(BR)DSX}$	$I_D = 10mA, V_{GS} = -12V$	8	—	—	
Gate threshold voltage		V_{th}	$V_{DS} = 10V, I_D = 200\mu A$	0.5	—	1.2	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 2.5V, I_D = 20A$	—	4.0	5.4	m Ω
			$V_{GS} = 4.5V, I_D = 20A$	—	3.1	4.1	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10V, I_D = 20A$	TBD	TBD	—	S
Input capacitance		C_{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$	—	1870	—	pF
Reverse transfer capacitance		C_{rss}		—	312	—	
Output capacitance		C_{oss}		—	1370	—	
Switching time	Rise time	t_r	<p>$V_{GS} = 5V, 0V$ $I_D = 20A$ $V_{DD} = 10V$ $Duty \leq 1\%, t_w = 10\mu s$</p>	—	TBD	—	ns
	Turn-ON time	t_{on}		—	TBD	—	
	Fall time	t_f		—	TBD	—	
	Turn-OFF time	t_{off}		—	TBD	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} = 16V, V_{GS} = 10V, I_D = 40A$	—	38	—	nC
			$V_{DD} = 16V, V_{GS} = 5V, I_D = 40A$	—	TBD	—	
Gate-source charge 1		Q_{gs1}	$V_{DD} = 16V, V_{GS} = 10V, I_D = 40A$	—	TBD	—	
Gate-drain ("miller") charge		Q_{gd}		—	8	—	
Gate switch charge		Q_{sw}		—	11	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	120	A
Forward voltage (diode)		V_{DSF}	$I_{DR} = 40A, V_{GS} = 0V$	—	—	-1.2	V

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